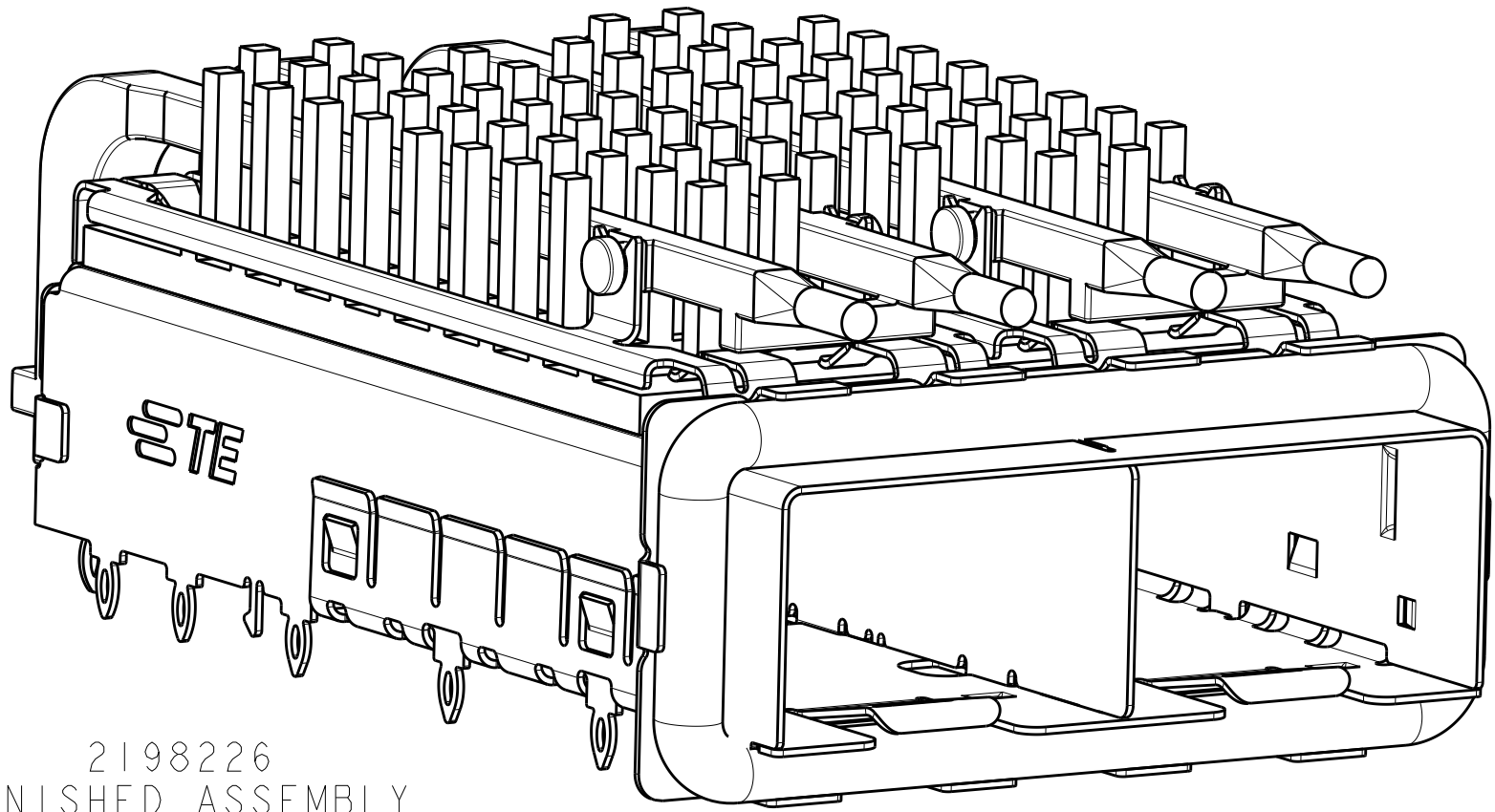
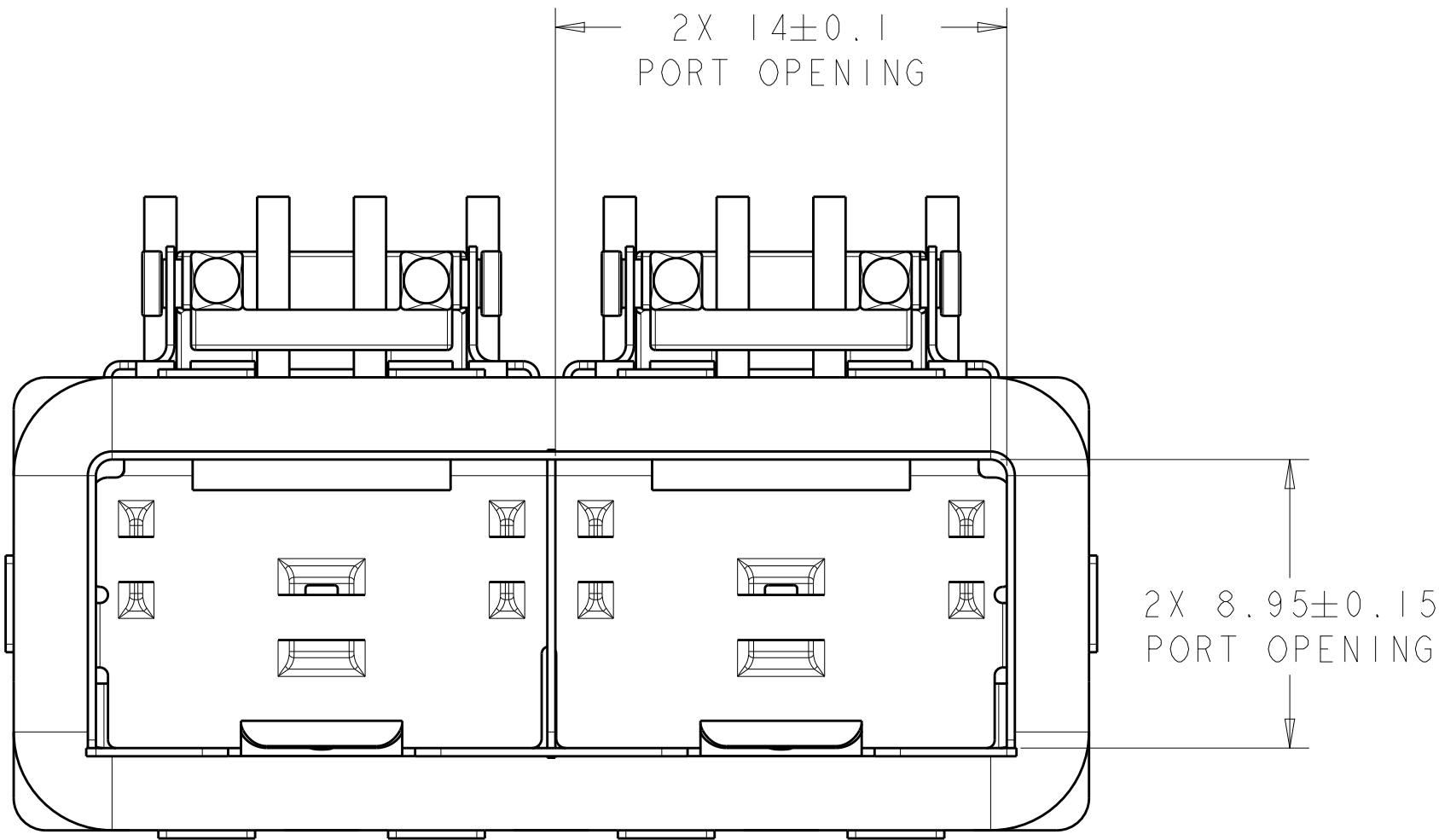
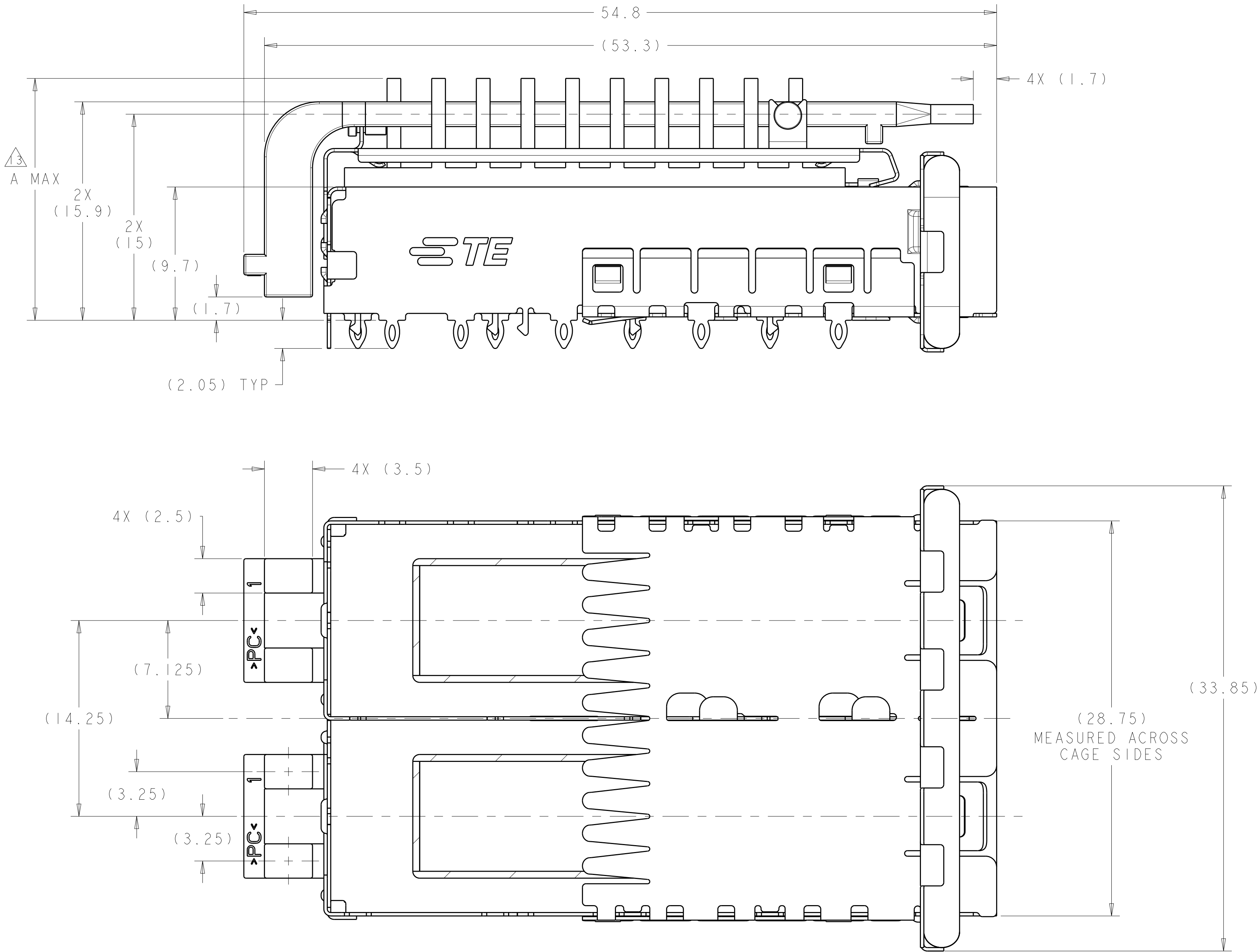




2198226
FINISHED ASSEMBLY
SCALE 4:1

- △ MATERIAL:
CAGE ASSEMBLY: 0.25mm THICK NICKEL SILVER ALLOY
GASKET RETENTION PLATE: STAINLESS STEEL
EMI GASKET: PLATED FILLED SILICONE
HEATSINK/LIGHTPIPE CLIP: STAINLESS STEEL
HEATSINK: ALUMINUM
LIGHTPIPE: POLYCARBONATE, CLEAR
- △ FINISH:
HEATSINK: ELECTROLESS NICKEL
HEATSINK/LIGHTPIPE CLIP: PASSIVATE
- △ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- △ PADS AND VIAS CHASSIS GROUND.
5. MATES WITH SFP MSA COMPLIANT RECIEVERS.
6. INTERPRETATION OF DATUM REFERENCE FRAME IN ACCORDANCE WITH SECT 4.4.1.1 OR ASME Y14.5M-1994.
- △ HOLE PATTERN REPEATS FOR EACH PORT, SPACING BETWEEN PORTS IS 14.25mm.
- △ REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- △ REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.

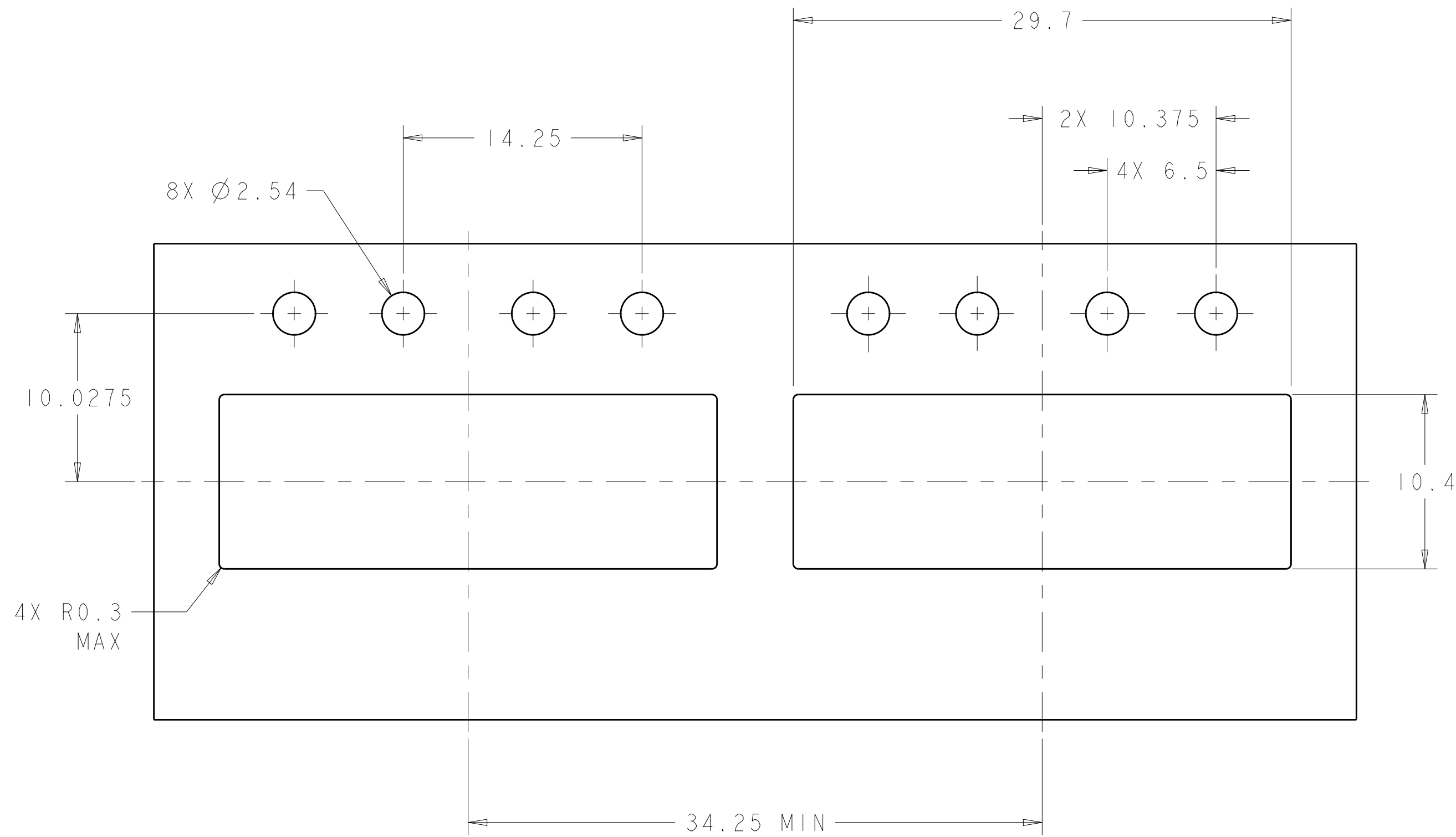
- △ MINIMUM PC BOARD THICKNESS:
SINGLE SIDED: 1.5mm
11. CERTAIN MATING TRANCEIVERS MAY REQUIRE ADDITIONAL PCB THICKNESS THAT WOULD NEED TO BE DETERMINED BY THE CUSTOMER.
12. PRODUCT COMPLIES WITH SPECIFICATION SFF-8433 IMPROVED PLUGGABLE FORM FACTOR FOR SFP+ GANGED CAGES.
- △ DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE.
- △ HEATSINK, HEATSINK CLIP, AND LIGHTPIPE SHIPPED UNASSEMBLED TO CAGE ASSEMBLY. CAGE ASSEMBLY TO BE PRESSED INTO PCB PRIOR TO ATTACHING HEATSINK, HEATSINK CLIP, AND LIGHTPIPE TO THE CAGE ASSEMBLY.
- △ PACKAGED AS A COMPLETE ASSEMBLY.



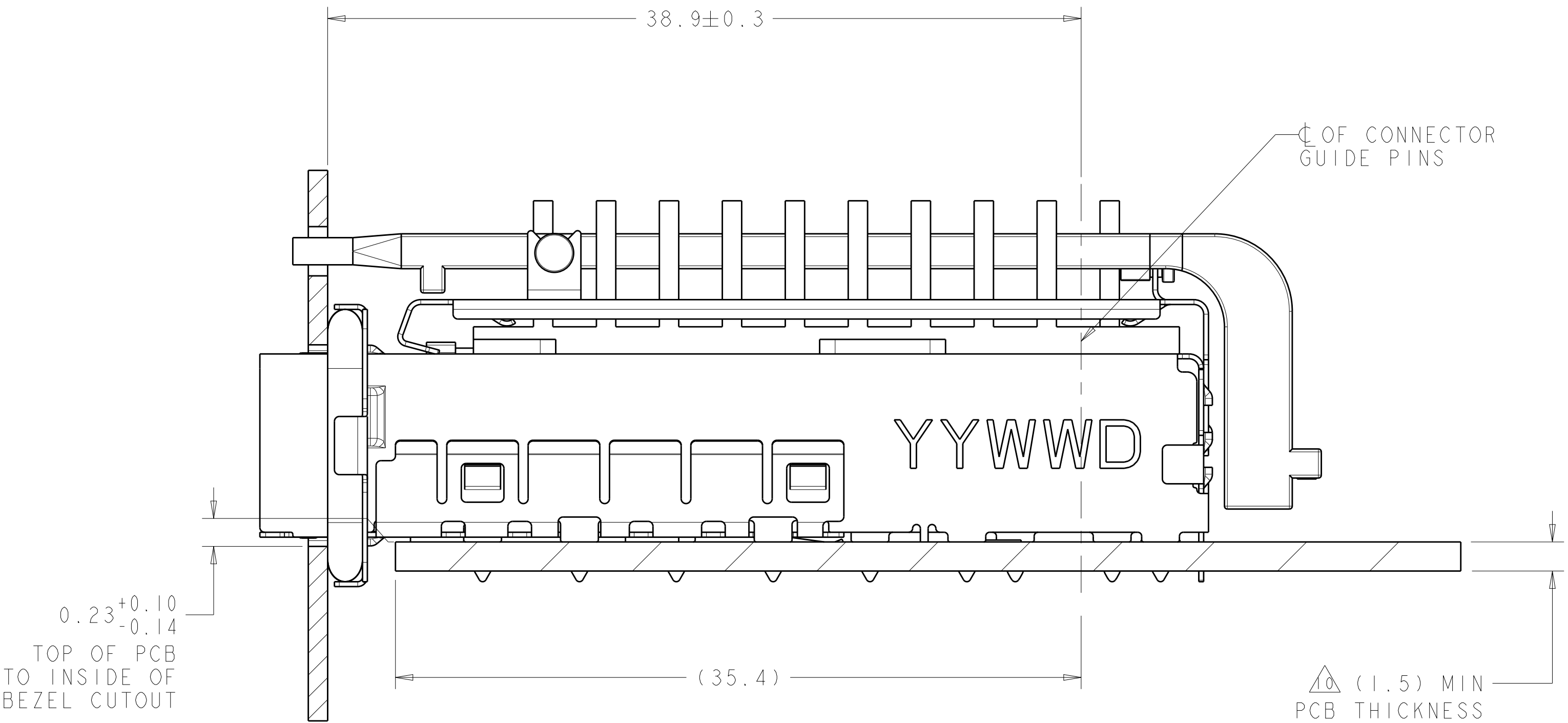
△ 3	22.5	NETWORKING, TALL	2198226-4
△ 3	18.1	NETWORKING, SHORT	2198226-3
△ 4	15.5	SAN	2198226-2
△ 4	13.2	PCI	2198226-1
	A MAX	APPLICATION	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. MATTHEWS 14OCT2011		
DIMENSIONS:		CHK M. SCHMITT 14OCT2011		
mm		APVD W. SCHMITT 14OCT2011		
		PRODUCT SPEC		
		108-2364		
		APPLICATION SPEC		
		114-13120		
MATERIAL		WEIGHT		
		-		
		CUSTOMER DRAWING		
		SCALE 5:1		
		SHEET 1 OF 3		
		REV A		

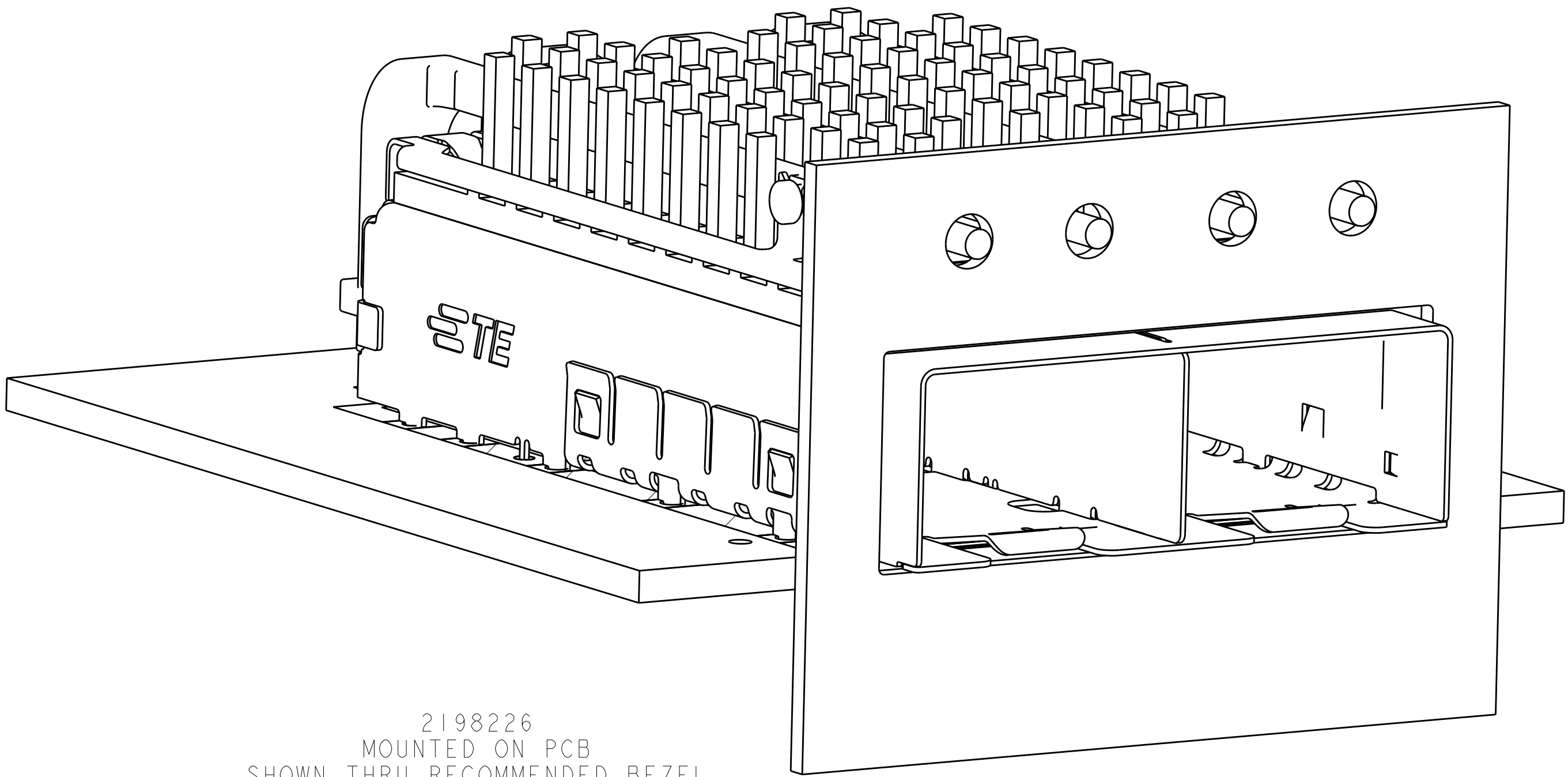
LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
GP	00	-	-	SEE SHEET 1	-	-	-



RECOMMENDED BEZEL CUTOUT
SCALE 4:1

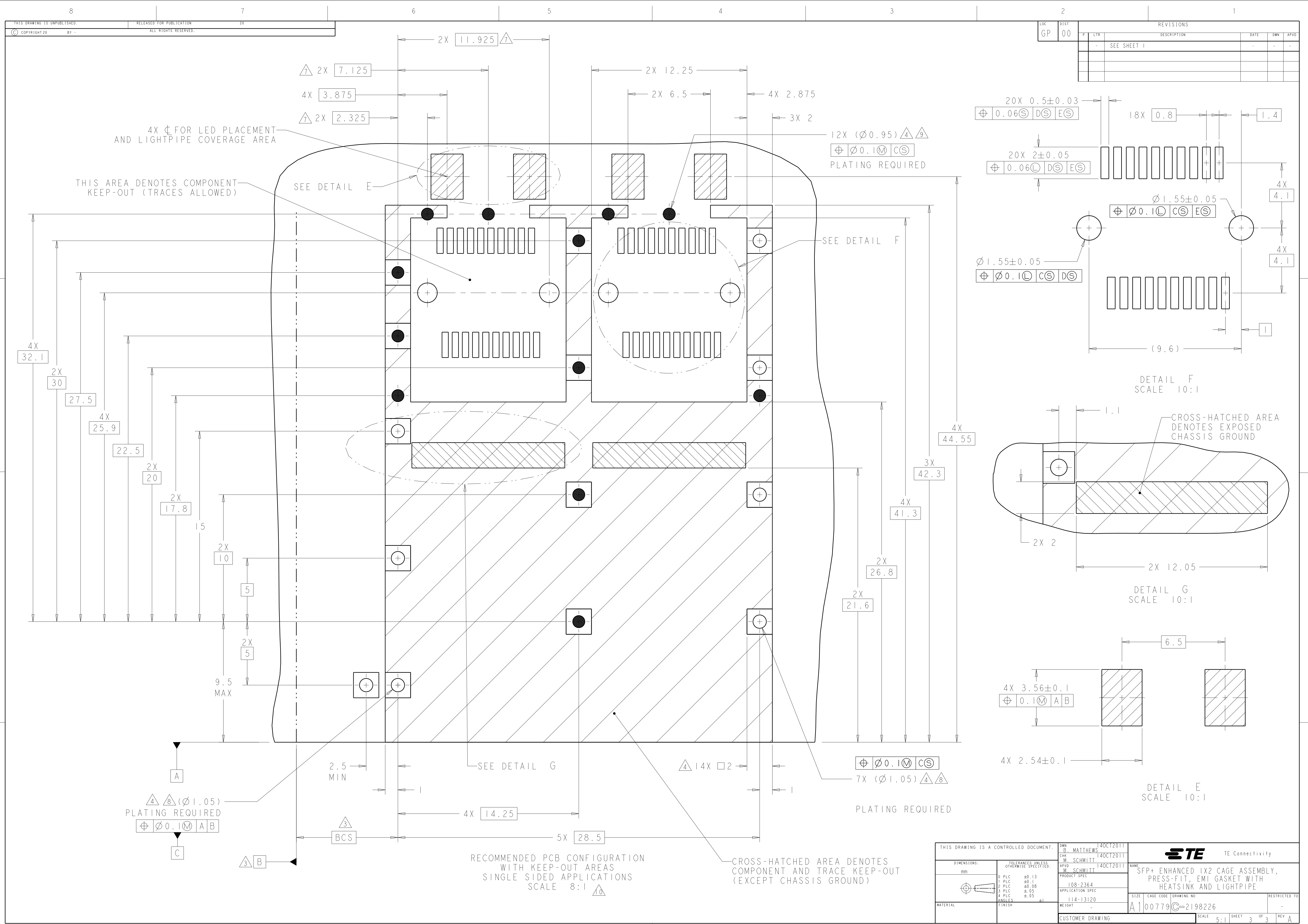


2198226
MOUNTED ON PC BOARD
SHOWN THRU RECOMMENDED BEZEL

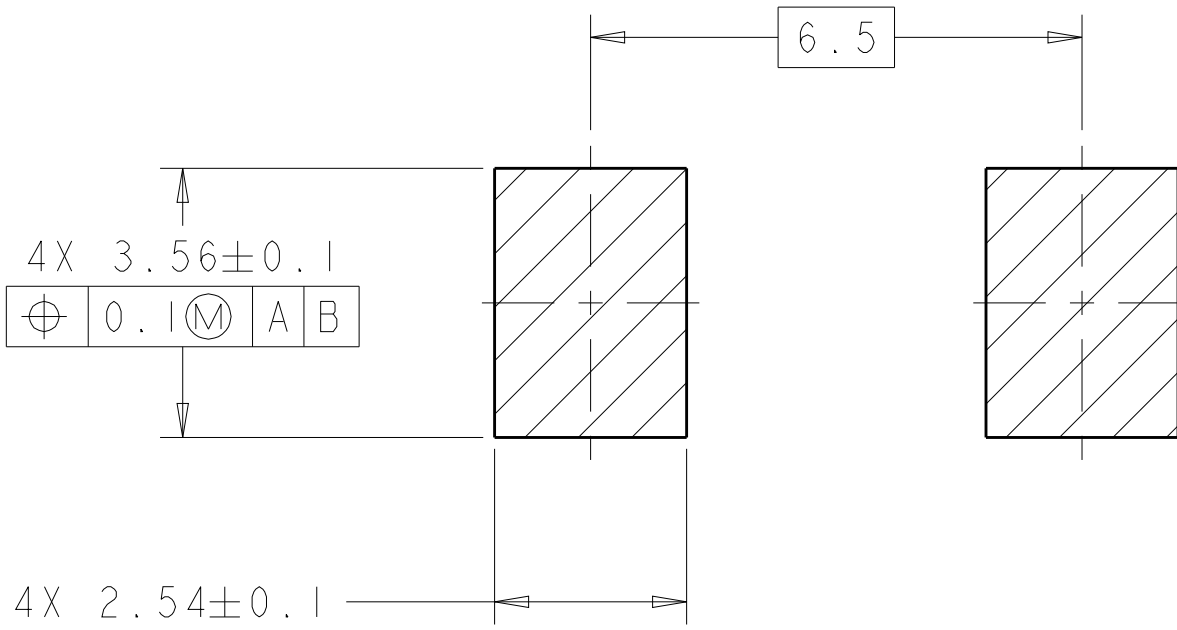
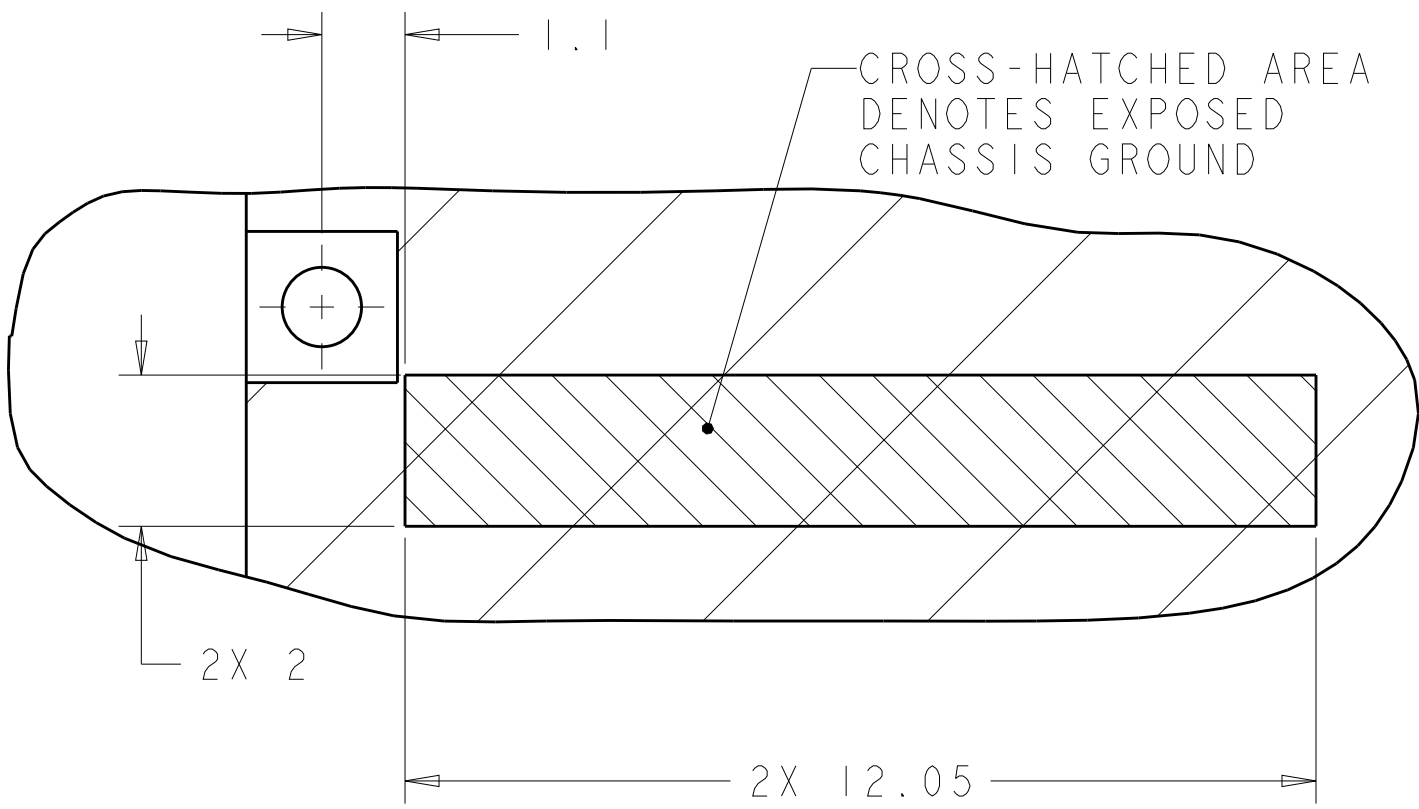
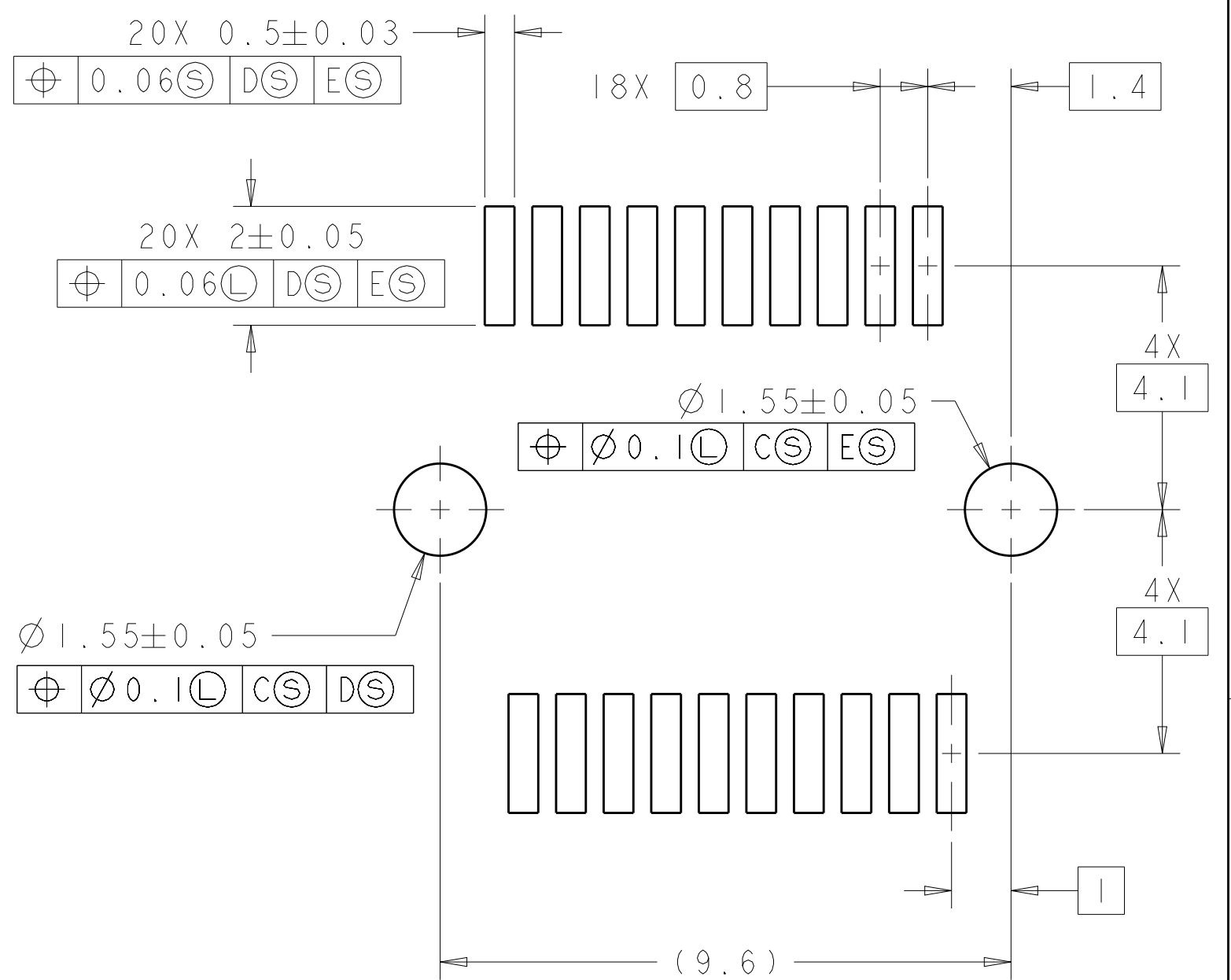


2198226
MOUNTED ON PCB
SHOWN THRU RECOMMENDED BEZEL

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. MATTHEWS CHK M. SCHMITT APVD M. SCHMITT	14OCT2011 14OCT2011 14OCT2011	TE Connectivity	
DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME	
mm		0 PLC ±0.13 1 PLC ±0.1 2 PLC ±0.08 3 PLC ±0.05 4 PLC ±0.05		SFP+ ENHANCED 1X2 CAGE ASSEMBLY, PRESS-FIT, EMI GASKET WITH HEATSINK AND LIGHTPIPE	
MATERIAL		FINISH		RESTRICTED TO	
				A100779C=2198226	
				SCALE 5:1 SHEET 2 OF 3 REV A	



LOC		DIST		REVISONS			
GP		00		P	LTR	DESCRIPTION	DATE
				-	-	SEE SHEET 1	-



4X $\varnothing$ FOR LED PLACEMENT
AND LIGHTPIPE COVERAGE AREA

THIS AREA DENOTES COMPONENT
KEEP-OUT (TRACES ALLOWED)

SEE DETAIL E

SEE DETAIL F

DETAIL F
SCALE 10:1

DETAIL G
SCALE 10:1

DETAIL E
SCALE 10:1

RECOMMENDED PCB CONFIGURATION
WITH KEEP-OUT AREAS
SINGLE SIDED APPLICATIONS
SCALE 8:1

CROSS-HATCHED AREA DENOTES
COMPONENT AND TRACE KEEP-OUT
(EXCEPT CHASSIS GROUND)

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN B. MATTHEWS	14OCT2011		
DIMENSIONS:		CHK M. SCHMITT	14OCT2011		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD M. SCHMITT	14OCT2011	NAME	
mm		PRODUCT SPEC		SFP+ ENHANCED 1X2 CAGE ASSEMBLY, PRESS-FIT, EMI GASKET WITH HEATSINK AND LIGHTPIPE	
0 PLC ±0.13		108-2364		SIZE	
1 PLC ±0.1		APPLICATION SPEC		CAGE CODE	
2 PLC ±0.08		114-13120		DRAWING NO	
3 PLC ±0.05		WEIGHT		RESTRICTED TO	
4 PLC ±0.05		CUSTOMER DRAWING		A100779C=2198226	
ANGLES FINISH		SCALE		5:1	
		SHEET		3 OF 3	
		REV		A	

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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